

Title (en)

PROCESS FOR PRODUCING CONTACTS ON ELECTRICAL COMPONENTS SUITABLE FOR A FLIP-CHIP ASSEMBLY

Title (de)

VERFAHREN ZUR HERSTELLUNG VON FÜR EINE FLIP- CHIP-MONTAGE GEEIGNETEN KONTAKTEN VON ELEKTRISCHEN
BAUELEMENTEN

Title (fr)

PROCEDE DE PRODUCTION DE CONTACTS DE COMPOSANTS ELECTRIQUES, CONVENANT AU MONTAGE PAR BOSSES SOUDEES

Publication

EP 0868744 A1 19981007 (DE)

Application

EP 96946147 A 19961216

Priority

- DE 9602412 W 19961216
- DE 19548046 A 19951221

Abstract (en)

[origin: DE19548046A1] In a process for producing contacts on SW components suitable for a flip-chip assembly, in which electrically conductive structures (3) on a substrate (1) are encapsulated by a cover (2), after the cover (2) has been produced, solderable layers (4) in contact with pads of the electrically conductive structures (3) are applied.

IPC 1-7

H01L 21/56; **H01L 21/60**; **H03H 9/05**

IPC 8 full level

H01L 21/60 (2006.01); **H01L 23/31** (2006.01); **H03H 3/02** (2006.01); **H03H 3/08** (2006.01)

CPC (source: EP KR US)

H01L 21/56 (2013.01 - KR); **H01L 23/3171** (2013.01 - EP US); **H03H 3/08** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US);
H01L 2924/3025 (2013.01 - EP US)

Citation (search report)

See references of WO 9723904A1

Designated contracting state (EPC)

CH DE FR GB LI

DOCDB simple family (publication)

DE 19548046 A1 19970626; **DE 19548046 C2 19980115**; CA 2241037 A1 19970703; CN 1105397 C 20030409; CN 1205800 A 19990120;
EP 0868744 A1 19981007; JP 2000502238 A 20000222; JP 4413278 B2 20100210; KR 100445569 B1 20041015; KR 19990072096 A 19990927;
US 6057222 A 20000502; WO 9723904 A1 19970703

DOCDB simple family (application)

DE 19548046 A 19951221; CA 2241037 A 19961216; CN 96199161 A 19961216; DE 9602412 W 19961216; EP 96946147 A 19961216;
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